

IN THE SPECIFICATION

Please amend the last two paragraphs of page 5 (*i.e.*, lines 26 through 29) as follows:

Figure 7 is a top plan view illustrating a plurality of integrated circuits constructed in accordance with another embodiment of the present invention; and

Figure 8 is a perspective view illustration a testing device and an integrated circuit constructed in accordance with one embodiment of the present invention; and.

Please insert the following paragraph after the last paragraph of page 5 (*i.e.*, after line 29):

Figure 9 is a flow chart indicating an exemplary method of forming and testing an integrated circuit in accordance with an embodiment of the present invention.

Please amend the paragraph set forth on page 10, lines 20-27 as follows:

A method for testing integrated circuits, such as set forth in Figure 9, includes providing an integrated circuit with the above-discussed alignment features. The alignment features, described in detail above, are used to mate with the testing equipment. For the embodiments illustrated in Figures 2 and 7, the alignment tab is aligned with a mating orifice on the testing equipment. For the embodiments illustrated in Figures 3-6, the alignment cut out on the lead frame is aligned with a projection on the testing equipment. The alignment features on the lead frame of the present invention are aligned with corresponding structure on the testing equipment.

Please amend the paragraph bridging pages 10 and 11 as follows:

Figure 8 illustrates one example of an integrated circuit 800 and a testing device 810 of the present invention during the testing process and which may be utilized in conjunction with the method depicted in Figure 9. Other configurations of the testing device 810 and the integrated circuit 800 are contemplated by the present invention. The testing device 810 has an alignment structure 814 and test contacts 812. The alignment structure 814 is coupled with an alignment feature 820 of the integrated circuit 800. The alignment structure 814 can take on a number of configurations including, but not limited to, posts, apertures, slots, and projections, depending on the configuration of the alignment feature on the device to be tested. The alignment structure 814 is mechanically coupled with the test contacts 812 such that consistent and proper alignment of the test contacts 812 with the leads 822 can be achieved. Aligning the testing device 810 using the alignment structure 814 and the alignment feature 820 beneficially provides for accurate alignment of the leads 822 of the integrated circuit 800 with test contacts 812.